WEST Refine Search Page 1 of 1

Refine Search Search Results Terms Documents L8 and cmp 6 US Pre-Grant Publication Full-Text Database US Patents Full-Text Database

Search:

Database:

L9			Refine Search
	Recall Text 🗢	Clear	Interrupt

Search History

DATE: Tuesday, September 21, 2004 Printable Copy Create Case

US OCR Full-Text Database EPO Abstracts Database

JPO Abstracts Database Derwent World Patents Index IBM Technical Disclosure Bulletins

Set Name	<u>Query</u>	Hit Count	Set Name
side by side			result set
DB=US	SPT; PLUR=YES; OP=ADJ		
<u>1.9</u>	L8 and cmp	6	<u>L9</u>
<u>L8</u>	L5 and (flow adj rate) and sccm and watts and nitride	8	<u>L8</u>
<u>1.7</u>	L4 and copper	5	<u>1.7</u>
<u>L6</u>	L3 and copper	8	<u>L6</u>
<u>L5</u>	L2 and copper	120	<u>15</u>
<u>L4</u>	L3 and ammonia	5	<u>L4</u>
<u>L.3</u>	L2 and (hydrogen adj plasma)	8	<u>1.3</u>
<u>L2</u>	porous near (low adj K)	130	<u>L2</u>
<u>L.1</u>	porous near (low adj K)	130	<u>L.1</u>

END OF SEARCH HISTORY

Hit List

Generate Collection Fwd Refs Bkwd Refs Clear Print **Generate OACS**

Search Results - Record(s) 1 through 6 of 6 returned.

1. Document ID: US 6790770 B2

L9: Entry 1 of 6

File: USPT

Sep 14, 2004

US-PAT-NO: 6790770

DOCUMENT-IDENTIFIER: US 6790770 B2

TITLE: Method for preventing photoresist poisoning

Full Title Chatton Front Review Classification Date Retainned Claims AMC Draws Do 2. Document ID: US 6737747 B2 May 18, 2004 L9: Entry 2 of 6 File: USPT

US-PAT-NO: 6737747

DOCUMENT-IDENTIFIER: US 6737747 B2

TITLE: Advanced BEOL interconnect structures with low-k PE CVD cap layer and method

thereof

Full Title Citation Front Review Classification Date Reference Claims KWC Draw De 3. Document ID: US 6723635 B1 Apr 20, 2004 File: USPT L9: Entry 3 of 6

US-PAT-NO: 6723635

DOCUMENT-IDENTIFIER: US 6723635 B1

TITLE: Protection low-k ILD during damascene processing with thin liner

Full Title Citation Front Review Classification Date Reference Claims KMC Draw De 4. Document ID: US 6576545 B1 Jun 10, 2003 L9: Entry 4 of 6 File: USPT

US-PAT-NO: 6576545

DOCUMENT-IDENTIFIER: US 6576545 B1

Record List Display Page 2 of 2

TITLE: Semiconductor devices with dual nature capping/ARC layers on fluorine doped silica glass inter-layer dielectrics and method of forming capping/ARC layers

5. Document ID: US		
L9: Entry 5 of 6	File: USPT	Feb 25, 2003
PAT-NO: 6525428 CUMENT-IDENTIFIER: US 652	25428 B1	
TLE: Graded low-k middle-	-etch stop layer for dual-inlaid	patterning
Full Title Citation Front Revi	iew Classification Date Reference	Elaims KiviC D
, TD 470	(202101 D1	
*****	File: USPT	Nov 27, 2001
L9: Entry 6 of 6 -PAT-NO: 6323121 CUMENT-IDENTIFIER: US 632	File: USPT	·
L9: Entry 6 of 6 -PAT-NO: 6323121 CUMENT-IDENTIFIER: US 632 TLE: Fully dry post-via-6	File: USPT 23121 B1 etch cleaning method for a damase	·
L9: Entry 6 of 6 -PAT-NO: 6323121 CUMENT-IDENTIFIER: US 632 TLE: Fully dry post-via-6	File: USPT	cene process
L9: Entry 6 of 6 -PAT-NO: 6323121 CUMENT-IDENTIFIER: US 632 TLE: Fully dry post-via-6	File: USPT 23121 B1 etch cleaning method for a damase	cene process
L9: Entry 6 of 6 -PAT-NO: 6323121 -CUMENT-IDENTIFIER: US 632 TLE: Fully dry post-via-6 FULL THE GREEN FOR REV	File: USPT 23121 B1 etch cleaning method for a damase Composition take Researce on Print Fwd Refs Bkwd	cene process
L9: Entry 6 of 6 -PAT-NO: 6323121 CUMENT-IDENTIFIER: US 632 TLE: Fully dry post-via-6	File: USPT 23121 B1 etch cleaning method for a damase	cene process

Next Page

Previous Page

Go to Doc#

Record List Display Page 1 of 2

Hit List

Clear Generate Collection Print Fwd Refs Bkwd Refs
Generate OACS

Search Results - Record(s) 1 through 5 of 5 returned.

1. Document ID: US 6693043 B1

L7: Entry 1 of 5

File: USPT

Feb 17, 2004

US-PAT-NO: 6693043

DOCUMENT-IDENTIFIER: US 6693043 B1

TITLE: Method for removing photoresist from low-k films in a downstream plasma

system

Full Title Citation Front Review Classification Date Reference Claims NWC Diam D.

Claims NWC Diam D.

L7: Entry 2 of 5 File: USPT Jan 6, 2004

US-PAT-NO: 6673725

DOCUMENT-IDENTIFIER: US 6673725 B2

TITLE: Semiconductor device and method of manufacturing the same

Full Title Citation Front Review Classification Date Reference Claims RMC Draw Do

3. Document ID: US 6638875 B2

L7: Entry 3 of 5 File: USPT Oct 28, 2003

US-PAT-NO: 6638875

DOCUMENT-IDENTIFIER: US 6638875 B2

TITLE: Oxygen free plasma stripping process

Full Title Citation Front Review Classification Date Reference Claims KMC Draw De

4. Document ID: US 6630406 B2

L7: Entry 4 of 5 File: USPT Oct 7, 2003

US-PAT-NO: 6630406

DOCUMENT-IDENTIFIER: US 6630406 B2

Record List Display Page 2 of 2

TITLE: Plasma ashing process

Full Title Citation Front Review	Classification Date Reference	Claims KWiC Draw D-

5. Document ID: US 62	81135 B1	
L7: Entry 5 of 5	File: USPT	Aug 28, 2001

US-PAT-NO: 6281135

DOCUMENT-IDENTIFIER: US 6281135 B1

TITLE: Oxygen free plasma stripping process

Full: Title: Citation Front Review Ci	assification Date Reference	Claims NMC Craw
Clear Generate Collection	Print Fwd Refs Bkwd Refs	Generate OACS
Terms	Documents	
L4 and copper		5

Display Format:	TI Change Format
-----------------	------------------

Previous Page Next Page Go to Doc#

Hit List

Generate Collection Fwd Refs Bkwd Refs Clear Print Generate OACS

Search Results - Record(s) 1 through 5 of 5 returned.

1. Document ID: US 6693043 B1

L4: Entry 1 of 5

File: USPT

Feb 17, 2004

US-PAT-NO: 6693043

DOCUMENT-IDENTIFIER: US 6693043 B1

TITLE: Method for removing photoresist from low-k films in a downstream plasma

system

Full Title Citation Front Review Classification Date Reference Claims RMC Draw Do 2. Document ID: US 6673725 B2 L4: Entry 2 of 5 Jan 6, 2004 File: USPT

US-PAT-NO: 6673725

DOCUMENT-IDENTIFIER: US 6673725 B2

TITLE: Semiconductor device and method of manufacturing the same

Full Title Citation Front Review Classification Date Reference Claims KWC Draw De 3. Document ID: US 6638875 B2

File: USPT

US-PAT-NO: 6638875

L4: Entry 3 of 5

DOCUMENT-IDENTIFIER: US 6638875 B2

TITLE: Oxygen free plasma stripping process

Full Title Citation Front Review Classification Date Reference Claims KMC Draw Do 4. Document ID: US 6630406 B2

L4: Entry 4 of 5

File: USPT

Oct 7, 2003

Oct 28, 2003

US-PAT-NO: 6630406

DOCUMENT-IDENTIFIER: US 6630406 B2

Record List Display Page 2 of 2

TITLE: Plasma ashing process

Full Title Citation Front Review	Classification Date Reference	C la lms KIMC Draw De
5. Document ID: US 62	281135 B1	
L4: Entry 5 of 5	File: USPT	Aug 28, 2001

US-PAT-NO: 6281135

DOCUMENT-IDENTIFIER: US 6281135 B1

TITLE: Oxygen free plasma stripping process

Full	e Citation Front Review Classification Date R	eference	Claims KWC Draw Dr
Clear	Generate Collection Print Fwo	Bkwd Refs	Generate OACS
T	erms	Documents	
L	3 and ammonia		5

Display Format: TI Change Format

Previous Page Next Page Go to Doc#